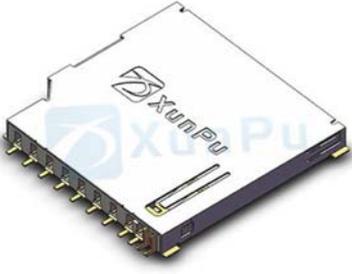


SD SOCKETS

技术参数 / Technical parameter



SD-102-ACP11
W25.50xD27.65xH2.80

PIN 数(Number of contacts) : 9+2PIN

耐电压(Withstand voltage) : 250V AC for 1 min

操作方式(Operation mode): 抽拉式/PUSH PULL

操作寿命(Operation life): 5,000 Cycles Min

温度范围(Operating temp): -40°C TO +80°C

焊接温度(Welding temperature): 260±5° 5s

额定负荷(Rated load): 0.5A PERP IN.

焊接方式(Welding mode): 贴片式/SMT

接触电阻(Contact resistance): 100mΩ max.

包装方式(Packaging method): 吸塑盘装/Tray

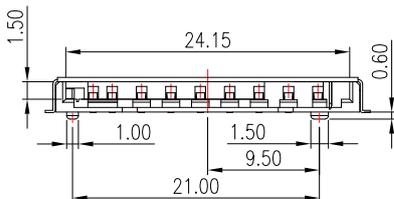
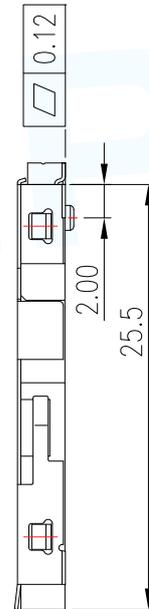
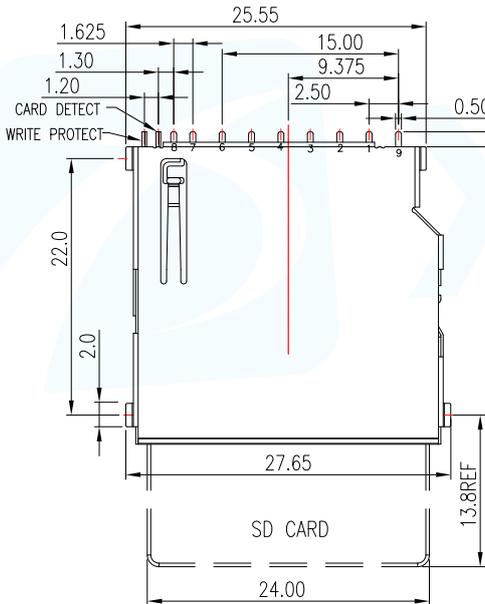
绝缘电阻(Insulation resistance): 1000MΩ min.

最小包装(Minimum packing): 50/PCS

外形尺寸 (UNIT:MM) / Size Chart

www.xunpudianzi.com

更多资料请参考技术选型档!



NOTES

1.MATERIAL

HOUSING: HIGH TEMPERATURE THERMOPLASTLC.

CONTACT: COPPER ALLOY.

SHELL: COPPER ALLOY.

2.PLATING

CONTACT AREA: GOLD PLATED ON CONTACT AREA.

SOLDER TAIL: 100u' MIN Sn PLATED

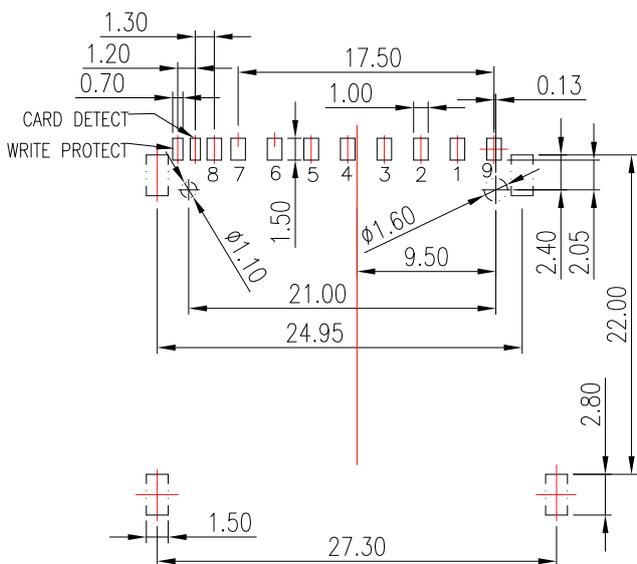
SHELL SOLDER AREA GOLD PLATED ON NICKEL UNDERPLATED.

3.SPECIFICATION

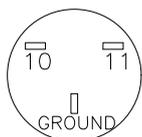
CONTACT RESISTANCE: 40 mOHMS

DIELECTRIC WITHSTANDING VOLTAGE: 500VAC MegOHMS

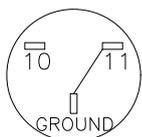
INSULATION RESISTANCE: 100 MegOHMS



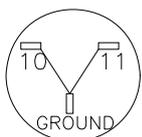
RECOMMENDED P.C.B LAYOUT
(General tolerance ±0.05)



WITHOUT CARD



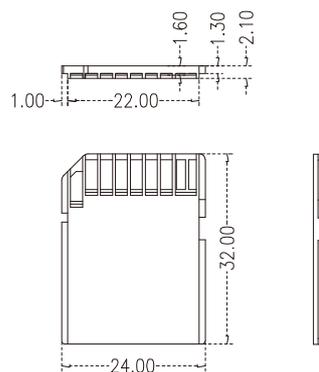
CARD INSERTED
WRITE PROTECT:LOCK



CARD INSERTED
WRITE PROTECT:UNLOCK

Circuit Diagram for Detect Switch

● SD CARD



● 引脚定义/Pin Definition

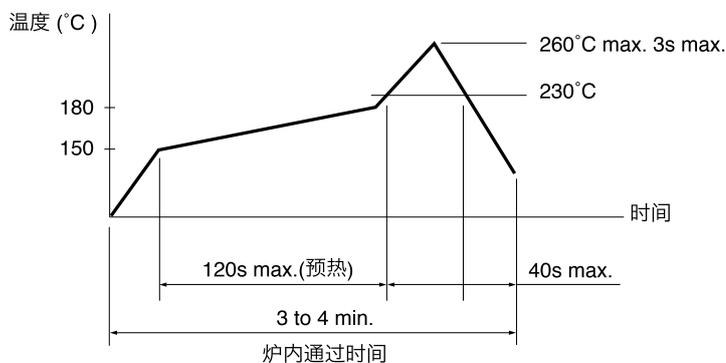
PIN#	NAME	DESCRIPTION
1#	CD/DAT3	Cord detect/data I/O
2#	CMD	Command
3#	VSS1	Ground
4#	VDD	Power
5#	CLK	Clock
6#	VSS2	Ground
7#	DAT0	Data I/O
8#	DAT1	Data I/O
9#	DAT2	Data I/O

10--WRITE PROTECT PIN
11--CARD DETECT PIN
GROUND(SHELL)--COMMON PIN

焊接条件 / Welding conditions

● 回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products
温度分布/Temperature distribution



● 手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

● 浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.

注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用Φ0.1~0.2的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。